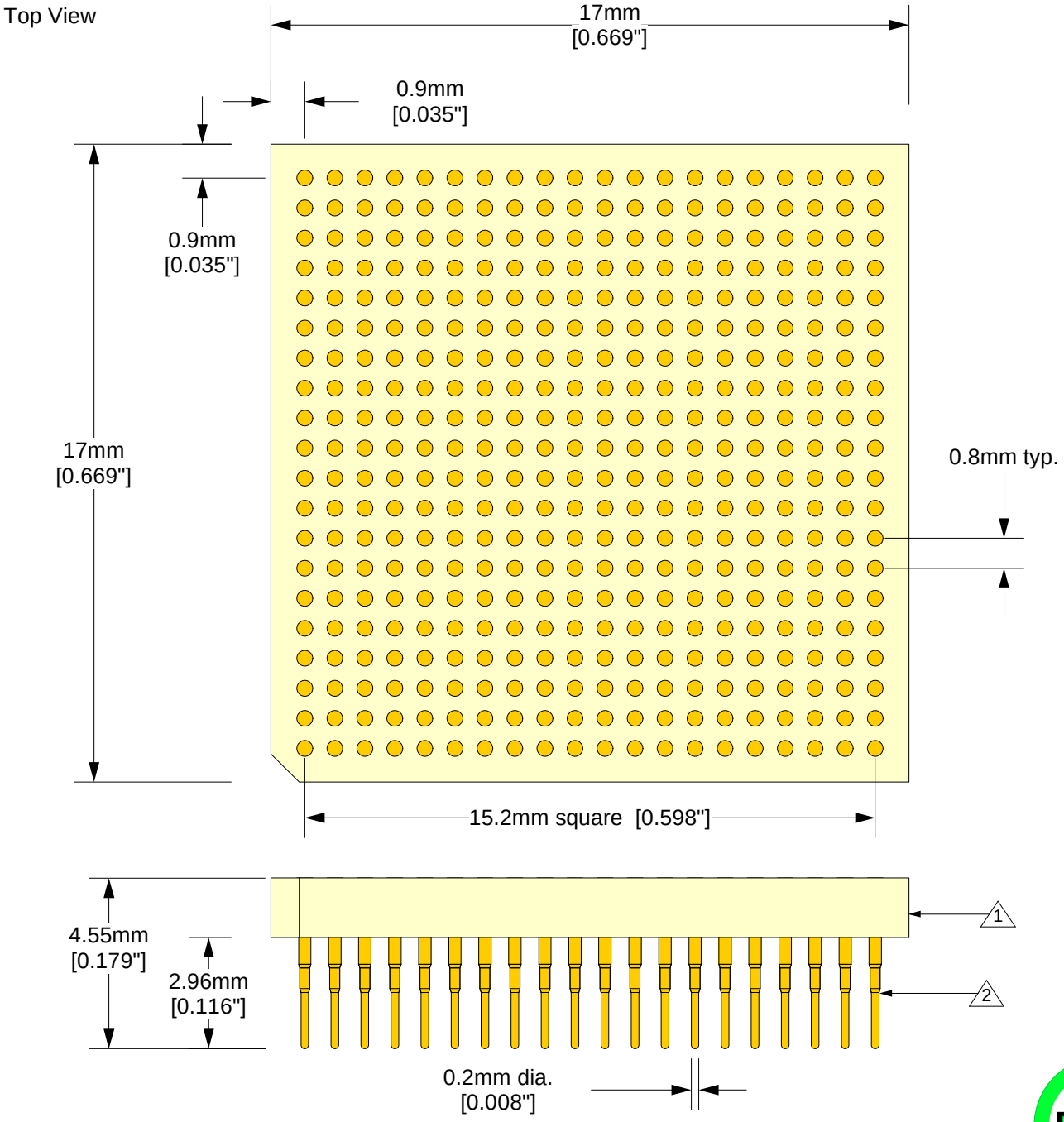


RoHS

1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. non clad

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket
400 position BGA surface mount land pattern to terminal pins (0.8mm centers, 20x20 array)

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA400H-61 Drawing	Status: Released	Scale: 6:1	Rev: C
© 2005 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: S.Natarajan	Date: 5/11/05	
	File: LS-BGA400H-61 Dwg.mcd	Modified: 01/18/13, DH	